PCN Number:		20220816000.1						Date:	August 16, 2022	
Title:										
Custom	Customer Contact: PCN Manager Dept: Quality Services									
Propose	d 1 <sup>st</sup> Shi	p Date	: Nov	14, 2022	Sample Pe			quests Sept 16 2022*		
*Sample	e reques	ts rece	ived afte	r Sept 10	6, 2022	will not be su	ported	l <b>.</b>		
Change										
Assembly Site					Design			Wafer Bump Site		
	embly Pro				Data Sheet			Wafer Bump Material		
	embly Mat		. Linu		Part number change			Wafer Bump Process		
	hanical S king/Shipp				Test Site			Wafer Fab Site   Wafer Fab Materials		
	Kiriy/Sirip	Jiriy/ Lai	beiling		☐ Test Process ☐			Wafer Fab Materials Wafer Fab Process		
	PCN Details									
Description of Change:										
Texas Instruments Incorporated is announcing the qualification of CDAT as an additional Assembly site for the TPS63070RNMR/T. Construction differences are as follows:										
			TI	TI Clark T.		Chengdu				
	Mount C	Compou	nd	422	22790	4223495				
				•						
Reason	for Chan	ge:								
Supply c	ontinuity									
Anticipa	ted impa	act on	Form, Fit	, Functio	n, Quali	ty or Reliabili	ty (posi	itive / r	negative):	
None										
Impact of	on Enviro	onmen	tal Rating	ıs						
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.										
RoHS				EACH		Green Statu		IEC 62474		
⊠ No C	Change		No Ch	ange 🛮 🖂 No Change			│ 図 No Change			
Changes	s to prod	luct ide	entificatio	n resulti	ing from	this PCN:				
Asseml	bly Site	Ass	embly Site (22L)	Origin Asser		embly Country Code (23L)		Ass	sembly City	
TIC	TI Clark		QAB			PHL		Ba	aguio City	
CD	CDAT CDA			CHN			Chengdu			
Sample p	roduct sl	hipping	label (no	t actual	product	label)				

TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:

MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04

OPT: ITEM:

5A (L)T0:3750



(1P) SN74LS07NSR (a) 2000 (D) 0336 31T)LOT: 3959047MLA 4W) TKY(1T) 7523483SI2

(2P) REV: (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA

(23L) ACO: MYS

**Product Affected:** 

TPS63070RNMR TPS63070RNMT



TI Information Selective Disclosure

## **Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: TPS63070RNMR	QBS Product Reference: TPS63070RNMR	QBS Process Reference: TPIC2020RTQ	QBS Package Reference: TPS543620RPY
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/77/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-			3/231/0
HBM	ESD - HBM	2500 V	-	1/3/0	-	1/3/0
CDM	ESD - CDM	500 V	1/3/0	1/3/0	-	1/3/0
LU	Latch-up	(per JESD78)	-	1/6/0	3/18/0	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	1/77/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	1/77/0	1/77/0
TC	Temperature Cycle - 65C/150C	500 Cycles	-	-	3/231/0	1/77/0
TC	Temperature Cycle, - 55/125C	700 Cycles	1/77/0	1/77/0	-	2/154/0
PD	Physical Dimensions		1/30/0			

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C: TPS63070RNMR
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
   The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
   The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
  Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210201-138427

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN ww admin team@list.ti.com

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